



Material Content Data Sheet



Sales Product Name		ICE3RBR1765JZ		Issued		20. July 2018		
MA#		MA001359396						
Package		PG-DIP-7-3		Weight*		644.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.779	0.59	0.59	5860	5860
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		75	
	non noble metal	zinc	7440-66-6	0.194	0.03		300	
	non noble metal	iron	7439-89-6	3.872	0.60		6003	
wire	non noble metal	copper	7440-50-8	157.218	24.38	25.02	243767	250145
	noble metal	gold	7440-57-5	0.430	0.07	0.07	666	666
	encapsulation	organic material	carbon black	1333-86-4	2.350	0.36		3643
encapsulation	plastics	epoxy resin	-	63.440	9.84		98364	
	inorganic material	silicondioxide	60676-86-0	404.138	62.65	72.85	626616	728623
leadfinish	non noble metal	tin	7440-31-5	6.540	1.01	1.01	10141	10141
plating	noble metal	silver	7440-22-4	1.594	0.25	0.25	2472	2472
glue	plastics	epoxy resin	-	0.236	0.04		366	
	noble metal	silver	7440-22-4	1.114	0.17	0.21	1727	2093
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com